

ON Semiconductor®

FDBL86561-F085

N-Channel PowerTrench[®] MOSFET 60 V, 300 A, 1.1 m Ω

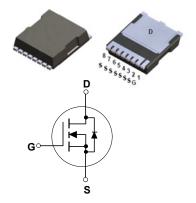
Features

- Typical $R_{DS(on)}$ = 0.85 m Ω at V_{GS} = 10V, I_D = 80 A
- Typical $Q_{g(tot)}$ = 170 nC at V_{GS} = 10V, I_D = 80 A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Automotive Engine Control
- PowerTrain Management
- Solenoid and Motor Drivers
- Integrated Starter/Alternator
- Primary Switch for 12V Systems





MOSFET Maximum Ratings $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter	Ratings	Units	
V _{DSS}	Drain-to-Source Voltage		60	V
V _{GS}	Gate-to-Source Voltage		±20	V
ı	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C = 25°C	300	^
ID	Pulsed Drain Current	T _C = 25°C	See Figure 4	Α
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	1167	mJ
D	Power Dissipation		429	W
P_{D}	Derate Above 25°C		2.86	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.35	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W

Notes:

- 1: Current is limited by bondwire configuration.
- 2: Starting $T_J = 25$ °C, L = 0.57mH, $I_{AS} = 64$ A, $V_{DD} = 40$ V during inductor charging and $V_{DD} = 0$ V during time in avalanche.
- 3: R_{0,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0,JC} is guaranteed by design, while R_{0,JA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Package Marking and Ordering Information

Device Marking	Device	Package			
FDBL86561	FDBL86561-F085	MO-299A	-	-	-

Max.

±100

Min.

Тур.

Units

nΑ

Electrical Characteristics $T_J = 25$ °C unless otherwise noted.

Parameter

Gate-to-Source Leakage Current

Off Characteristics							
B _{VDSS}	Drain-to-Source Breakdown Voltage	$I_D = 250 \mu A$	V _{GS} = 0V	60	-	-	V
I _{DSS}	Drain-to-Source Leakage Current	$V_{DS} = 60V$	$T_J = 25^{\circ}C$	-	-	1	μΑ
		$V_{GS} = 0V$	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	-	3	mA

 $V_{GS} = \pm 20V$

Test Conditions

On Characteristics

Symbol

 I_{GSS}

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$		2.0	3.0	4.0	V
R _{DS(on)}	Drain to Source On Resistance	I _D = 80A,	$T_J = 25^{\circ}C$	-	0.85	1.1	$m\Omega$
		V _{GS} = 10V	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	1.5	2.2	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	$V_{DS} = 30V, V_{GS} = 0V,$ f = 1MHz		-	13650	-	pF
C _{oss}	Output Capacitance			-	3375	-	pF
C _{rss}	Reverse Transfer Capacitance			-	255	-	pF
R_g	Gate Resistance	f = 1MHz		-	2.3	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	V _{GS} = 0 to 10V	V _{DD} = 48V	-	170	220	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0 \text{ to } 2V$ $I_D = 80A$		-	24	32	nC
Q_{gs}	Gate-to-Source Gate Charge		_	-	56	-	nC
Q_{gd}	Gate-to-Drain "Miller" Charge			-	24	-	nC

Switching Characteristics

t _{on}	Turn-On Time		-	-	137	ns
t _{d(on)}	Turn-On Delay		-	45	-	ns
t _r	Rise Time	V _{DD} = 30V, I _D = 80A,	-	61	-	ns
t _{d(off)}	Turn-Off Delay	V_{GS} = 10V, R_{GEN} = 6Ω	-	80	-	ns
t _f	Fall Time		-	41	-	ns
t _{off}	Turn-Off Time		-	-	156	ns

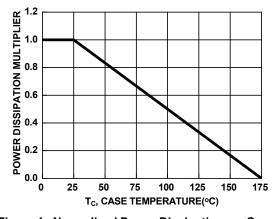
Drain-Source Diode Characteristics

V _{SD}	ISOURCE-TO-Drain Dioge Voltage	I _{SD} =80A, V _{GS} = 0V	-	-	1.25	V
		I_{SD} = 40A, V_{GS} = 0V	-	-	1.2	V
t _{rr}	Reverse-Recovery Time	$I_F = 80A$, $dI_{SD}/dt = 100A/\mu s$,	-	107	139	ns
Q _{rr}	Reverse-Recovery Charge	V _{DD} =48V	-	183	265	nC

Note:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.

Typical Characteristics



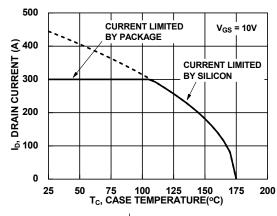


Figure 1. Normalized Power Dissipation vs. Case Temperature

Figure 2. Maximum Continuous Drain Current vs.

Case Temperature

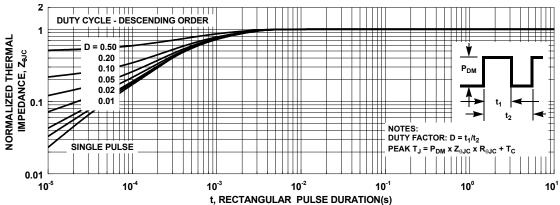


Figure 3. Normalized Maximum Transient Thermal Impedance

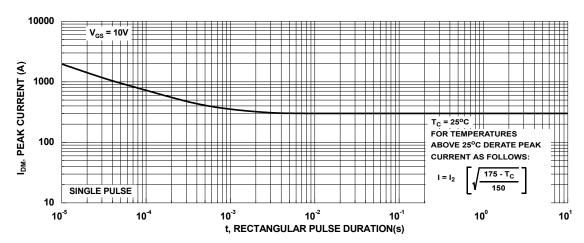
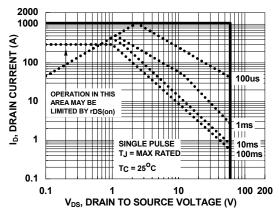


Figure 4. Peak Current Capability

Typical Characteristics



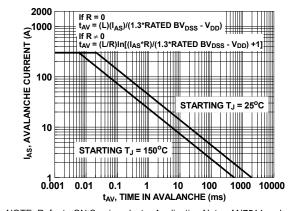
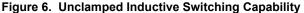
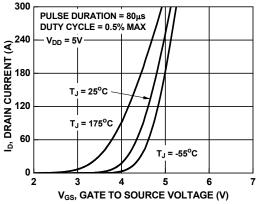
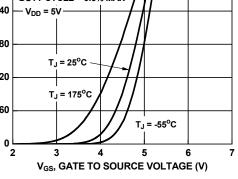


Figure 5. Forward Bias Safe Operating Area

NOTE: Refer to ON Semiconductor Application Notes AN7514 and AN7515







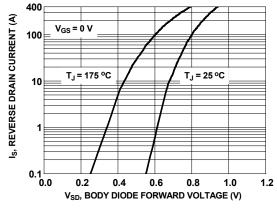
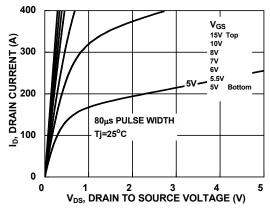


Figure 7. Transfer Characteristics

Figure 8. Forward Diode Characteristics



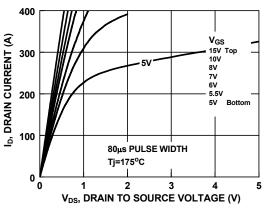


Figure 9. Saturation Characteristics

Figure 10. Saturation Characteristics

Typical Characteristics

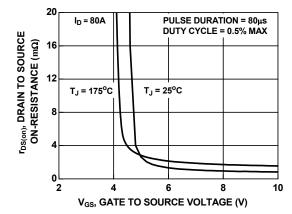


Figure 11. R_{DSON} vs. Gate Voltage

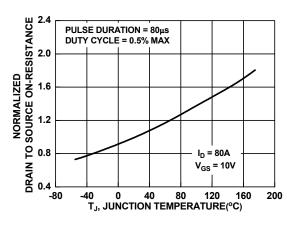


Figure 12. Normalized R_{DSON} vs. Junction Temperature

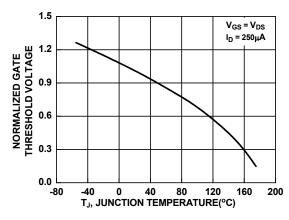


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

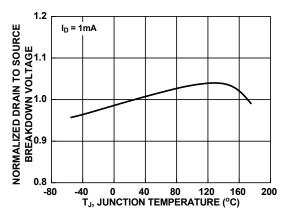


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

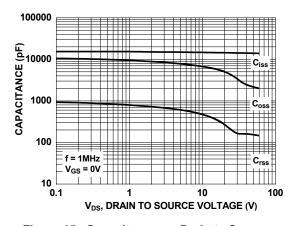


Figure 15. Capacitance vs. Drain to Source Voltage

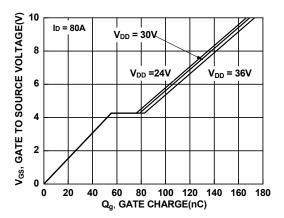


Figure 16. Gate Charge vs. Gate to Source Voltage

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